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### (54) FUNCTIONAL DATA PROGRAMMING AND READING IN A MEMORY

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(52) U.S. Cl.

CPC ........... G11C 16/10 (2013.01); G06F 11/1008 (2013.01); G11C 16/0483 (2013.01); G11C 16/26 (2013.01); G11C 16/349 (2013.01)

## (58) Field of Classification Search

USPC ............ 365/185.03, 185.09, 185.17, 185.18, 365/185.24, 185.33

See application file for complete search history.

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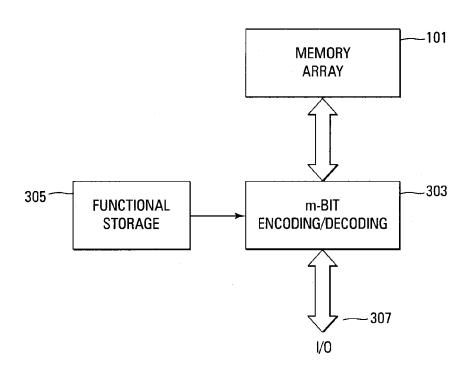
JР 2009230205 10/2009

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#### (57)ABSTRACT

Methods for functional programming memory cells and apparatuses are disclosed. One such method for functional programming includes encoding a group of data with a function to generate representative data and programming the representative data to the memory. In one embodiment, the representative data is a pattern of threshold voltages to be programmed to a group of memory cells.

# 26 Claims, 7 Drawing Sheets



<sup>\*</sup> cited by examiner

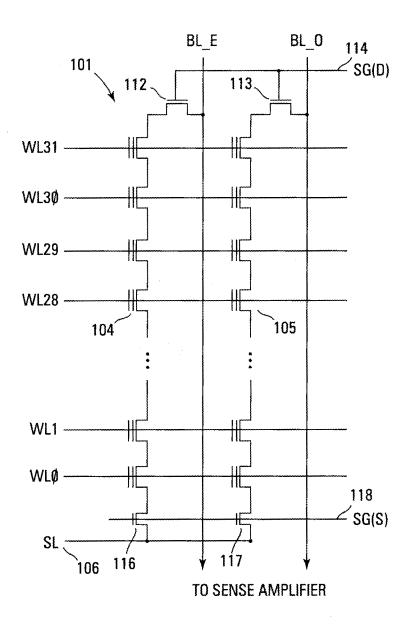
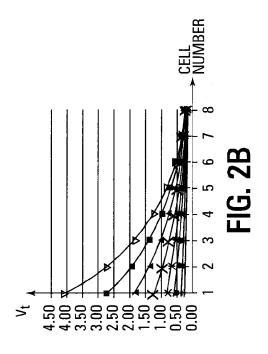
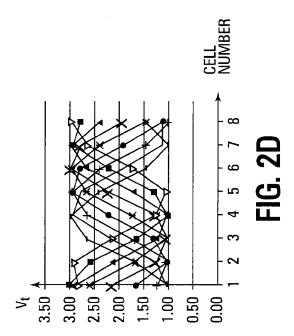
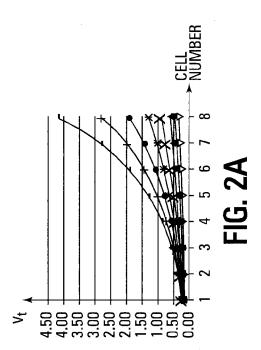
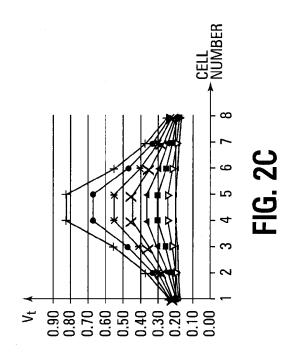


FIG. 1









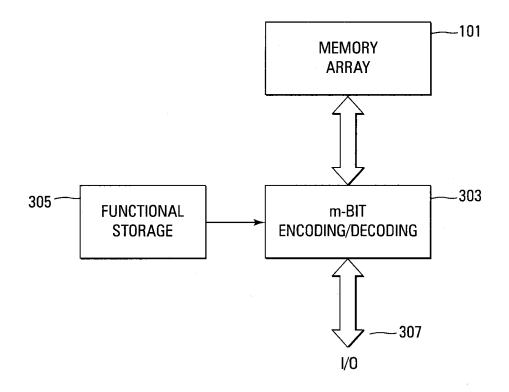


FIG. 3

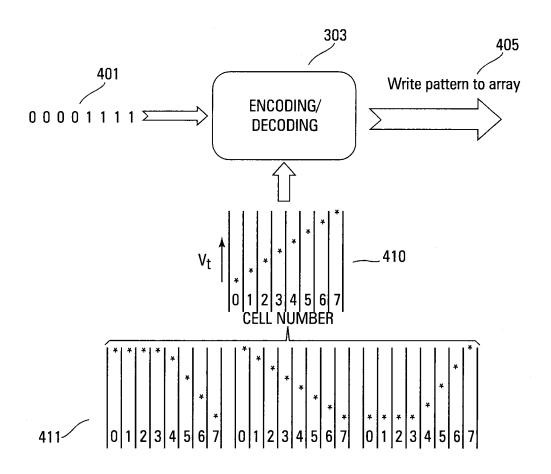


FIG. 4

0.00	1.00	1.58	2.00	2.32	2.58	2.81	3.00
l	7	က	4	22	9	7	∞
0.25	0.37	0.55	0.83	1.23	1.84	2.74	4.09
0.24	0.34	0.48	0.68	96.0	1.36	1.93	2.74
0.23	0.30	0.41	0.55	0.75	1.01	1.36	1.84
0.21	0.27	0.35	0.45	0.58	0.75	0.96	1.23
0.20	0.25	0.30	0.37	0.45	0.55	0.68	0.83
0.19	0.23	0.26	0.30	0.35	0.41	0.48	0.55
0.18	0.20	0.23	0.25	0.27	0.30	0.34	0.37
0.18	0.18	0.19	0.20	0.21	0.23	0.24	0.25
0.05	0.1	0.15	0.2	0.25	0.3	0.35	0.4
0.1667	0.1667	0.1667	0.1667	0.1667	0.1667	0.1667	0.1667
	0.05 0.18 0.18 0.19 0.20 0.21 0.23 0.24 0.25 1	0.05 0.18 0.19 0.20 0.21 0.23 0.24 0.25 1   0.1 0.18 0.20 0.25 0.27 0.30 0.34 0.37 2	0.05 0.18 0.18 0.19 0.20 0.21 0.23 0.24 0.25 1   0.1 0.18 0.20 0.23 0.25 0.27 0.30 0.34 0.37 2   0.15 0.19 0.26 0.30 0.35 0.41 0.48 0.55 3	0.05 0.18 0.19 0.20 0.21 0.23 0.24 0.25 1   0.1 0.18 0.20 0.23 0.25 0.27 0.30 0.34 0.37 2   0.15 0.19 0.26 0.30 0.35 0.41 0.48 0.55 3   0.2 0.20 0.25 0.37 0.45 0.55 0.68 0.83 4	0.05 0.18 0.19 0.20 0.21 0.23 0.24 0.25 1   0.1 0.18 0.20 0.23 0.25 0.27 0.30 0.34 0.37 2   0.15 0.19 0.26 0.30 0.35 0.41 0.48 0.55 3   0.2 0.20 0.25 0.30 0.37 0.45 0.55 0.68 0.83 4   0.25 0.21 0.27 0.35 0.45 0.55 0.68 0.83 4   0.25 0.27 0.35 0.45 0.75 0.96 1.23 5	0.05 0.18 0.19 0.20 0.21 0.23 0.24 0.25 1   0.1 0.18 0.20 0.23 0.25 0.27 0.30 0.34 0.37 2   0.15 0.19 0.23 0.25 0.30 0.35 0.41 0.48 0.55 3   0.2 0.20 0.25 0.30 0.37 0.45 0.55 0.68 0.83 4   0.25 0.21 0.27 0.35 0.45 0.58 0.75 0.96 1.23 5   0.3 0.23 0.41 0.55 0.75 1.01 1.36 1.84 6	0.1667 0.05 0.18 0.19 0.20 0.21 0.23 0.24 0.25 1 0.00   0.1667 0.1 0.18 0.20 0.25 0.27 0.30 0.34 0.37 2 1.00   0.1667 0.15 0.19 0.26 0.26 0.30 0.35 0.41 0.48 0.55 3 1.58   0.1667 0.2 0.20 0.25 0.30 0.37 0.45 0.55 0.68 0.83 4 2.00   0.1667 0.25 0.21 0.27 0.35 0.45 0.58 0.75 0.96 1.23 5 2.32   0.1667 0.3 0.23 0.30 0.41 0.55 0.75 1.01 1.36 1.84 6 2.58   0.1667 0.35 0.24 0.36 0.48 0.66 1.36 1.93 2.74 7 2.81

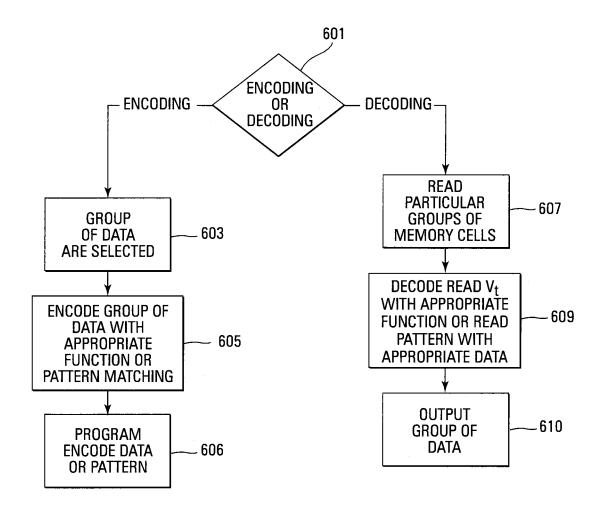


FIG. 6

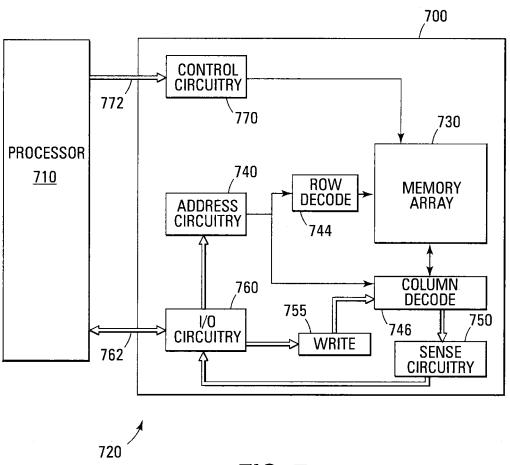


FIG. 7

# FUNCTIONAL DATA PROGRAMMING AND READING IN A MEMORY

### TECHNICAL FIELD

The present invention relates generally to memory and a particular embodiment relates to functional data programming in non-volatile memory.

### BACKGROUND

Flash memory devices have developed into a popular source of non-volatile memory for a wide range of electronic applications. Flash memory devices typically use a one-transistor memory cell that allows for high memory densities, high reliability, and low power consumption. Common uses for flash memory include personal computers, personal digital assistants (PDAs), digital cameras, and cellular telephones. Program code and system data such as a basic input/output system (BIOS) are typically stored in flash memory devices for use in personal computer systems.

A flash memory is a type of memory that can be erased and reprogrammed in blocks instead of one byte at a time. A typical flash memory comprises a memory array organized in columns and rows. Changes in threshold voltage of the memory cells, through programming of charge storage structures (e.g., floating gates or charge traps) or other physical phenomena (e.g., phase change or polarization), determine the data value of each cell. The cells are usually grouped into blocks. Each of the cells within a block can be electrically programmed, such as by charging the charge storage structure. The data in a cell of this type is determined by the presence or absence of the charge in the charge storage structure. The charge can be removed from the 35 charge storage structure by an erase operation.

As the physical size of memory arrays is decreased in order to increase the density of memory devices, the reduced proximity of the memory cells can result in problems with capacitive coupling. For example, charge storage structure-to-charge storage structure (e.g., floating gate-to-floating gate) capacitive coupling between adjacent memory cells can cause the programming of one memory cell to "pull-up" the threshold voltage of an adjacent memory cell to a higher threshold voltage. This coupling can result in errors reading the affected memory cell since its threshold voltage can be increased beyond a normal target voltage for a particular programmed state.

Some types of read errors can be corrected by error correction coding (ECC). However, ECC uses additional 50 controller time that could be used for other functions and can take up additional memory locations in the memory array that can be used as user memory.

For the reasons stated above and for other reasons stated below that will become apparent to those skilled in the art 55 upon reading and understanding the present specification, there is a need in the art to reduce the impact of charge storage structure-to-charge storage structure coupling in memory.

# BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 shows a schematic diagram of one embodiment of a portion of a memory array.

FIGS. 2A-2D show graphs of embodiments of possible 65 functions in accordance with the functional data programming of the present disclosure.

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FIG. 3 shows a block diagram of one embodiment of an encoding and decoding block as used with the memory array of FIG. 1.

FIG. 4 shows a block diagram of one embodiment of encoding and decoding of data using pattern recognition in accordance with the embodiment of FIG. 3.

FIG. 5 shows a table of threshold voltages resulting from one embodiment of a functional encoding of data.

FIG. **6** shows a flowchart of one embodiment of a method for functional data programming and reading in a memory.

FIG. 7 shows a block diagram of one embodiment of a system that can incorporate the method for functional data programming and reading.

### DETAILED DESCRIPTION

In the following detailed description, reference is made to the accompanying drawings that form a part hereof and in which is shown, by way of illustration, specific embodiments. In the drawings, like numerals describe substantially similar components throughout the several views. Other embodiments may be utilized and structural, logical, and electrical changes may be made without departing from the scope of the present disclosure. The following detailed description is, therefore, not to be taken in a limiting sense.

FIG. 1 illustrates a schematic diagram of one embodiment of a portion of a NAND architecture memory array 101 comprising series strings of non-volatile memory cells. The present embodiments of the memory array are not limited to the illustrated NAND architecture. Alternate embodiments can use NOR or other architectures as well.

The memory array 101 comprises an array of non-volatile memory cells (e.g., floating gate) arranged in columns such as series strings 104, 105. Each of the cells is coupled drain to source in each series string 104, 105. An access line (e.g., word line) WL0-WL31 that spans across multiple series strings 104, 105 is coupled to the control gates of each memory cell in a row in order to bias the control gates of the memory cells in the row. Data lines, such as even/odd bit lines BL\_E, BL\_O, are coupled to the series strings and eventually coupled to sense circuitry (such as sense amplifier circuitry) that detects the state of each cell by sensing current or voltage on a selected bit line.

Each series string 104, 105 of memory cells is coupled to a source line (SL) 106 by a source select gate 116, 117 (e.g., transistor) and to an individual bit line BL\_E, BL\_O by a drain select gate 112, 113 (e.g., transistor). The source select gates 116, 117 are controlled by a source select gate control line SG(S) 118 coupled to their control gates. The drain select gates 112, 113 are controlled by a drain select gate control line SG(D) 114.

In a typical prior art programming of the memory array, each memory cell is individually programmed as either a single level cell (SLC) or a multiple level cell (MLC). The prior art uses a cell's threshold voltage (V<sub>t</sub>) as an indication of the data stored in the cell. For example, in an SLC, a V<sub>t</sub> of 2.5V might indicate a programmed cell while a V<sub>t</sub> of -0.5V might indicate an erased cell. An MLC uses multiple V<sub>t</sub> ranges that each indicates a different state. Multiple level cells can take advantage of the analog nature of a traditional flash cell by assigning a bit pattern to a specific V<sub>t</sub> range.

Instead of using individual memory cells as isolated information node storage, the present embodiments for functional data programming use a functional relationship between a group of memory cells. The group can be along a word line, along a bit line, or a matrix of both. As subsequently described in greater detail, the data to be stored

is encoded with a mathematical function that can be expressed as fi(m), where "m" is an integer number of cells and "i" is an integer number of functional variations.

For example, m=3 signifies that three physical memory cells will be used to store one of eight different functional 5 variations signified by i=1, 2, . . . , 8. Thus each function denoted by i=1 to i=8 will represent eight variations of mathematical functions resulting in 3 bits of binary data. That is, i will have max value L (in this case L=8) to result in storing n-bits of binary data (in this case n=3) within m 10 physical cells (in this case m=3). One could store n=3 bits of data on m=4 physical cell to reduce probability of error at extra memory cost or store n=5 bits of information on m=4 physical cells for a more cost effective storage. In this case L= $2^5$ =32 different functional variations will be needed 15 to store 5 bits on 4 physical cells.

FIGS. 2A-2D illustrate four possible embodiments of functions that can be used to program into groups of memory cells. These functions are for purposes of illustration only as other functions can be used.

The illustration of the group of memory cells comprising eight memory cells is also used for purposes of illustration. Alternate embodiments can use other quantities of memory cells in the group of memory cells that represent the data being programmed. In one embodiment, a number of 25 memory cells can be chosen to create a balance between function resolution, error sensitivity, and storage density.

Each of the functions of FIGS. 2A-2D use groups of eight memory cells to achieve eight bits of data. This needs 28=256 variations of a function(s) to be stored. The Y-axis 30 of each function represents the threshold voltage (V<sub>t</sub>) levels for each individual memory cell. The X-axis represents the memory cell's number, or other designation, with an assigned point in the particular illustrated function. Each plot of each graph represents a different variation of the 35 particular function represented in its respective graph.

For example, FIG. 2A illustrates a graph of an increasing exponential function. This graph can be represented by the function  $Ae^{(B^*m)}$  where A and B are constants that can be chosen by empirical testing to find the best error correction 40 and noise immunity and m is the number of cells being programmed. This graph is discussed in greater detail with reference to the table of FIG. 5. The remaining graphs illustrated in FIGS. 2B-2D illustrate different functions in substantially the same manner.

FIG. 2B illustrates a graph of a decreasing exponential function. FIG. 2C illustrates a graph of a combination of both of the embodiments of FIGS. 2A and 2B. FIG. 2D illustrates a periodic function.

FIG. 3 illustrates a block diagram of one embodiment of 50 an encoding and decoding block 303 that can be used with the memory array 101 of FIG. 1. The m-bit encoding and decoding block 303 encodes data received over the Input/Output (I/O) connections 307 and decodes data from the memory array 101. The encoding and decoding can be 55 accomplished using a function (e.g., mathematical function).

The value of "m" of the encoding and decoding block 303 determines the number of memory cells within the array 101 to be programmed with the encoded data. The m-cell encoding and decoding block 303 can be implemented in software, 60 hardware, or both software and hardware.

The function to be used in encoding the data can be stored in the functional storage **305**. The functional storage **305** can be some type of memory (e.g., ROM or flash memory) that is resident on the memory device. In another embodiment, 65 the functional storage can be separate from the memory device and the one or more functions can be used to generate

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particular patterns that can be used by the encoding and decoding block 303 as described subsequently with reference to FIG. 4.

In one embodiment, the functional storage 305 can choose a function appropriate to specific characteristics of the memory device and architecture in response to changing memory parameters. A different function can be chosen to encode/decode data in response to changing memory parameters (e.g., noise, memory aging) and/or to reduce charge storage structure-to-charge storage structure coupling and improve write performance. For example, one function might provide better noise immunity than other functions. Thus, if a read/verify of the memory detects that the reliability of programming of memory cells is degraded due to a greater than normal noise condition, a new function can be chosen to improve noise immunity. Similarly, as memory cells age (e.g., experience an increased number of program/ erase cycles), their programming characteristics change. A different function can be selected to encode/decode data so 20 as to compensate for the changing programming character-

In one embodiment, the functional storage 305 can be implemented outside of the memory integrated circuit and the patterns generated by the one or more functions could then be stored within the memory integrated circuit. In another embodiment, both the functional storage and the patterns generated by the one or more functions can be stored within the memory integrated circuit.

The number of cells "m" that are programmed as part of the group of memory cells can also be changed as needed to increase/decrease the resolution of the error correction coding inherently provided by the functional programming. A larger "m" can provide improved ECC over a smaller "m" at the expense of reduced memory density.

The encoding and decoding block 303 can also provide decoding of data read from the memory array 101. The already encoded data from the array 101 can be decoded using the same function used to encode it. Thus, the data are read from the memory array, decoded by the decoding block 303 and output over the I/O connections 307.

FIG. 4 illustrates another embodiment for functionally encoding and decoding data using pattern writing and pattern recognition. This embodiment can be executed within the encoding and decoding block 303 of FIG. 3.

In the embodiment of FIG. 4, one or more functions are used to generate a plurality of particular patterns 411 that can be stored in the memory device. Each pattern is generated by a particular function operating on a particular group of data. For example, assuming a group of data comprises eight digits (e.g., bits) 401, data comprising 00001111 would have one particular pattern 410 that is used to represent that particular group of data. Thus, the embodiment of FIG. 4 uses pattern matching to both encode data to be programmed to the memory array and decode data from the memory array. The choice of the optimum set of functions depends on memory array architecture and process technology and is the key factor enabling better and more reliable data storage. This choice and determination of the set of functions is known to those skilled in the art.

Each particular group of bits with its corresponding representative pattern is stored for subsequent decoding of the data read from the memory array. A table of particular groups of bits and each of their corresponding representative patterns can be stored in a table in memory.

Referring to the example pattern 410 of FIG. 4, it can be seen that each pattern is a matrix of cell numbers along the bottom and V, levels. The example pattern 410 shows an

increasing V, for each subsequent cell from cell  $\bf 0$  to cell  $\bf 7$  of the eight cell pattern. Thus, each pattern is a particular pattern of cell numbers and threshold voltages within a particular group of cells.

As an example encoding operation, input data 401 from 5 the I/O connections is input to the encoding and decoding block 303. The input data 401 is grouped into a particular group of bits (e.g., 8 bits) for selection of the particular pattern 410, from a plurality of patterns 411, that has been assigned to represent that particular group of bits. This 10 pattern is then programmed to the memory array 405 as the pattern of threshold voltages.

A decode operation operates in a reverse fashion from the encode operation. The data are read from the memory array as a particular pattern of threshold voltages. This pattern is 15 then matched in the decoding block 303 to determine the particular group of data that the pattern represents. The group of data is then output over the I/O connections to the user. In an alternate embodiment, the pattern is operated on by an inverse function to the function that originally 20 encoded the data in order to generate the group of data.

FIG. 5 illustrates a table of one embodiment for encoding groups of data to eight memory cells. This table is for purposes of illustration only since any of the illustrated parameters (e.g., A, B, n) can change for different embodi- 25 ments

For example, in the illustrated embodiment, A is a constant while B is a variable. Alternate embodiments can have a constant B while A is the variable or both A and B can be variables. The values of A and B can be determined based on a combination of the mathematical function used, the memory technology (e.g., floating gate), and/or the problem being addressed by the encoding (e.g., noise, aging, coupling).

The table of FIG. **5** is a tabular representation of the graph 35 of FIG. **2**A. The table includes columns for the values of parameters A and B as described previously. The table also includes columns for the threshold voltage b(m) (e.g., b(1)-b(8)) for each of the eight memory cells being programmed, where "m" is the m<sup>th</sup> cell in the group of cells being encoded 40 and b(m) is the threshold voltage for each of the memory cells, of a particular function, that results from the encoding process.

The table further includes columns for the functional variation (e.g., 1-8) and the number of bits each of those 45 variations can be used to represent. Each functional variation represents what data is being encoded. For example, functional variation 1 might represent a binary "00000001" and functional variation 2 might represent a binary "00000010".

In the embodiment of FIG. 5, using the values of A, B, and 50 n from the table, the mathematical function b(m)=A\*exp(B, m-cell) was used to generate the threshold voltage for each physical cell from 1 to m, where "m-cell" is the m<sup>th</sup> cell in the group of cells. The resulting threshold voltages for each memory cell are plotted in the graph of FIG. 2A.

Alternate embodiments can use functions other than the exponential function used in FIG. 5. For example, the function A\*sin(B\*m-cell) could be used to encode a group of bits to generate the threshold voltage for each memory cell. The resulting encoded data from this function is shown 60 in the graph of FIG. 2D.

FIG. 6 illustrates a flowchart of one embodiment of a method for encoding and decoding data in a memory device. A determination is initially made whether a decoding operation or an encoding operation is to be performed 601.

If an encoding operation is to be performed, a group of data are selected having a particular quantity of bits 603. The

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quantity of cells for each group of data can be selected as a balance between resolution of the function, error sensitivity, and/or desired storage density in the memory device.

The group of data can then be encoded 605 by matching the data with a representative pattern of threshold voltages (e.g., indirectly using a function) or by encoding the data using an appropriate function (e.g., directly using a function), as discussed previously. The encoded data can then be programmed to the memory cells 606.

If a decoding operation is to be performed, a read operation is performed on a particular group of memory cells 607 that includes data that was functionally stored. The read operation reads a particular pattern of threshold voltages for each of a plurality of memory cells in the group of memory cells. The pattern of read threshold voltages can then be decoded 609 by using an inverse of the function used to encode the data or by comparing the read pattern of threshold voltages with a plurality of particular patterns to determine which pattern matches. The group of data associated with the matching pattern is the decoded data. The group of decoded data can then be output 610.

The method for encoding and decoding data can be used in 3-D NAND or other storage devices that store information by variable electrical or physical property values on memory elements. In the case of a 3D memory, one could cross the 2-dimensional plane in choosing the group of m-cells that could store the n-bits of data. In this case, the mathematical functions or patterns could take lines, surfaces or volume representations.

FIG. 7 illustrates a functional block diagram of a memory device 700 as part of a memory system 720. The memory device 700 is coupled to a controller 710. The controller 710 may be a microprocessor or some other type of controlling circuitry. The memory device 700 has been simplified to focus on features of the memory that are helpful in understanding the present invention.

The memory device 700 includes an array 730 of non-volatile memory cells, such as the one illustrated previously in FIG. 1. The memory array 730 is arranged in banks of word line rows and bit line columns. In one embodiment, the columns of the memory array 730 are comprised of series strings of memory cells as illustrated in FIG. 1. As is well known in the art, the connections of the cells to the bit lines determines whether the array is a NAND architecture, an AND architecture, or a NOR architecture.

Address buffer circuitry **740** is provided to latch address signals provided through the I/O circuitry **760**. Address signals are received and decoded by a row decoder **744** and a column decoder **746** to access the memory array **730**. It will be appreciated by those skilled in the art, with the benefit of the present description, that the number of address input connections depends on the density and architecture of the memory array **730**. That is, the number of addresses increases with both increased memory cell counts and increased bank and block counts.

The memory device 700 reads data in the memory array 730 by sensing voltage or current changes in the memory array columns using sense circuitry. The sense circuitry 750, in one embodiment, is coupled to read and latch a row of data from the memory array 730. The sense circuitry 750 can include the page buffers as described herein. Data input and output buffer circuitry 760 is included for bidirectional data communication as well as address communication over a plurality of data connections 762 with the controller 710. Write circuitry 755 is provided to write data to the memory array.

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Memory control circuitry 770 decodes signals provided on control connections 772 from the controller 710. These signals are used to control the operations on the memory array 730, including data read, data write (program), and erase operations. The memory control circuitry 770 may be a state machine, a sequencer, or some other type of control circuitry to generate the memory control signals. In one embodiment, the memory control circuitry 770 is configured to execute the embodiments for encoding and decoding.

The flash memory device illustrated in FIG. 7 has been simplified to facilitate a basic understanding of the features of the memory. A more detailed understanding of internal circuitry and functions of flash memories are known to those skilled in the art.

### CONCLUSION

In summary, one or more embodiments of the disclosed methods for functional programming and reading in a memory can encode and decode data using a function either directly or indirectly. The functionally encoded data can be programmed to memory and may result in reduced effects from coupling and disturb and reduced use of error correction coding.

Although specific embodiments have been illustrated and described herein, it will be appreciated by those of ordinary skill in the art that any arrangement that is calculated to achieve the same purpose may be substituted for the specific embodiments shown. Many adaptations of the invention will 30 be apparent to those of ordinary skill in the art. Accordingly, this application is intended to cover any adaptations or variations of the invention. It is intended that this invention be limited only by the following claims and equivalents thereof.

What is claimed is:

- 1. A method for functional programming in a memory, the method comprising:
  - encoding a group of data responsive to a mathematical 40 function selected from a plurality of mathematical functions to generate representative data comprising a particular pattern of threshold voltages of a plurality of patterns of threshold voltages to be programmed to a group of memory cells; and
  - programming the representative data corresponding to the group of memory cells to the memory;
  - wherein the selected mathematical function is selected, at least in part, in response to a value of the group of data; and
  - wherein a value of each mathematical function of the plurality of mathematical functions for a particular memory cell of the group of memory cells is dependent at least upon a cell number of the particular memory cell within the group of memory cells.
- 2. The method of claim 1 wherein the representative data comprise a plurality of threshold voltages.
- 3. The method of claim 1 wherein the mathematical function is further selected responsive to a memory parameter of the memory.
- 4. The method of claim 2 wherein the encoding the group of data comprises:

selecting the group of data; and

generating the plurality of threshold voltages, wherein each of the plurality of threshold voltages corresponds to a respective memory cell of the group of memory cells.

- 5. The method of claim 1 wherein the encoding the group of data comprises matching the group of data with the particular pattern of threshold voltages.
- 6. The method of claim 1, wherein a variation of the selected mathematical function represents the group of data.
- 7. The method of claim 1, wherein a parameter of the selected mathematical function is variable.
  - **8**. The method of claim **1**, further comprising:
  - wherein the selected mathematical function corresponds to a particular set of bit patterns for the group of memory cells; and
  - wherein a different mathematical function of the plurality of mathematical functions corresponds to a different set of bit patterns for the group of memory cells.
  - 9. The method of claim 8, further comprising:
  - wherein the particular set of bit patterns comprises a number of bit patterns equal to a number of memory cells of the group of memory cells.
  - 10. The method of claim 8, further comprising:
  - wherein a value of the selected mathematical function for the particular memory cell of the group of memory cells is further dependent upon a particular bit pattern of the particular set of bit patterns that corresponds to the group of data.
- 11. A method for functional programming in a memory, the method comprising:
  - encoding a group of data responsive to a function to generate representative data; and
  - programming the representative data to a number of memory cells of the memory equal to a number of elements of the group of data;
  - wherein the encoding the group of data responsive to the function to generate the representative data comprises determining a particular pattern of a plurality of patterns corresponding to the function that represents the group of data;
  - wherein a number of patterns of the plurality of patterns corresponding to the function is less than  $2^m$  where m is the number of elements of the group of data; and
  - wherein programming the representative data to the memory comprises the programming the particular pattern to the memory.
- 12. The method of claim 11 wherein the determining the 45 particular pattern comprises reading a table in memory comprising particular groups of bits and each of their corresponding representative patterns.
  - 13. The method of claim 11 wherein each of the patterns is a matrix of cell numbers and threshold voltages.
  - 14. The method of claim 11 and further comprising generating each of the plurality of patterns with a function operating on a respective group of data.
  - 15. The method of claim 14 wherein each of the plurality of patterns represents a different group of data.
    - 16. The method of claim 11, further comprising:
    - implementing error correction at a resolution, the resolution of error correction determined by the number of elements of the group of data.
    - 17. The method of claim 11, further comprising:
    - selecting the function in response to a bit pattern of the group of data.
  - 18. The method of claim 11, wherein the selecting the function comprises selecting the function from a plurality of functions, and wherein each function of the plurality of functions corresponds to a respective set of bit patterns that can be represented by the number of elements of the group of data.

- 19. An apparatus comprising: an array of memory cells; and
- an encoder coupled to the array of memory cells, wherein the encoder is configured to encode a group of data in accordance with a mathematical function selected, at 5 least in part in response to a bit pattern of the group of data, from a plurality of mathematical functions to generate a representative pattern of threshold voltages of a plurality of patterns of threshold voltages to be programmed to the array of memory cells;

wherein the group of data comprises a plurality of digits of data;

wherein each mathematical function of the plurality of mathematical functions corresponds to a particular number of patterns of threshold voltages of the plurality 15 of patterns of threshold voltages; and

wherein the particular number of patterns of threshold voltages for each mathematical function of the plurality of mathematical functions is less than a number of patterns of digits that can be represented by a number 20 of digits of data of the plurality of digits of data.

20. The apparatus of claim 19 wherein the encoder comprises an encoder/decoder, wherein the encoder/decoder

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is further configured to decode a read pattern of threshold voltages into a group of data.

- 21. The apparatus of claim 19 wherein the encoder is configured to change the number of digits of data of the plurality of digits of data to increase or decrease a resolution of error correction coding.
- 22. The apparatus of claim 21 wherein the encoder is further configured to operate on the group of data to generate the representative pattern of threshold voltages.
- 23. The apparatus of claim 21 wherein the encoder is further configured to operate on a constant times the group of data to generate the representative pattern of threshold voltages.
- **24**. The apparatus of claim **19** and further comprising a memory, configured to store the plurality of mathematical functions, coupled to the encoder.
- **25**. The apparatus of claim **19** wherein the apparatus is a 3-D NAND memory device.
- **26**. The apparatus of claim **25** wherein the plurality of patterns of threshold voltages is stored in memory cells across multiple planes of the memory device.

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